

AMENDMENT OF THE CLAIMS

Claims 1-17 (Cancelled)

18. (Previously Presented) A method for incorporating a thinned chip into a smart card, comprising applying the chip to a surface of the smart card externally.

19. (Previously Presented) The method according to claim 18, including applying the chip with its front side pointing outside to the surface of the smart card and wherein the card and chip are provided with conductive paths.

20. (Previously Presented) The method according to claim 18 or 19, including incorporating the chip into a cavity in the surface of the smart card.

21. (Previously Presented) The method according to claim 18, including pressing the chip into the surface of the smart card flush under the action of heat.

22. (Previously Presented) The method according to claim 18, including coating the chip located on the surface of the smart card with a protective lacquer.

Claims 23-26 (Cancelled)

27. (Previously Presented) A smart card comprising a smart card having at least one thinned chip disposed on a surface of the smart card.

28. (Previously Presented) The smart card according to claim 27, wherein the chip is disposed with its front side outside on the smart card and conductive paths are applied to the smart card and the chip on the outside.

29. (Previously Presented) The smart card according to claim 27 or 28, wherein the conductive paths are printed.

30. (Previously Presented) The smart card according to claim 27 or 28, wherein the chip is disposed in a cavity in the surface of the smart card.

31. (Previously Presented) The smart card according to claim 27, wherein the chip is pressed into the surface of the smart card flush.

32. (Previously Presented) The smart card according to claim 27, wherein the chip is coated with a protective lacquer.

33. (New) A method for incorporating a thinned chip into a smart card having a plastic card body, comprising the step of:

applying the chip to a surface of the card body externally;
wherein the chip is permanently secured by the card body.

34. (New) The method according to claim 33, further comprising the step of applying the chip having a front side facing outwardly from the surface of the card body;

wherein the card body and chip are provided with conductive paths.

35. (New) The method according to claim 33 or 34, further comprising the step of incorporating the chip into a cavity in the surface of the card body.

36. (New) The method according to claim 33, further comprising the step of pressing the chip into the surface of the card body flush under the action of heat wherein the material of the card body surrounds the entirety of the chip with the

exception of a front side of the chip facing outwardly from the surface of the card body.

37. (New) The method according to claim 33, further comprising the step of coating the chip located on the surface of the card body with a protective lacquer.

38. (New) The method according to claim 33, wherein the card body consists a single card body.

39. (New) A smart card comprising a plastic card body having at least one thinned chip disposed on a surface of a card body, wherein the chip is permanently secured by the card body.

40. (New) The smart card according to claim 39, wherein the chip is disposed with its front side outside on the card body and conductive paths are applied to the card body and the chip on the outside.

41. (New) The smart card according to claim 39, wherein the conductive paths are printed.

42. (New) The smart card according to claim 39 or 40, wherein the chip is disposed in a cavity in the surface of the card body.

43. (New) The smart card according to claim 39, wherein the chip is pressed into the surface of the card body flush.

44. (New) The smart card according to claim 39, wherein the chip is coated with a protective lacquer.

45. (New) The smart card according to claim 39, wherein the card body consists a single card body.

46. (New) A method for incorporating a thinned chip into a smart card having a plastic card body, comprising the steps of:

providing a plurality of contacts on an external surface of the card body;
placing a chip over at least portions of the plurality of contacts;
applying the chip to the external surface of the card body; and
permanently securing the chip to the card body.

47. (New) The method according to claim 46, further comprising the step of incorporating at least portions of the contacts into the card body.

48. (New) The method according to claim 46, further comprising the step of incorporating the entirety of the contacts into the card body.